SPECIFICATION

REFOND P/N

RF-A2B3F-G218-G1

Mass Production

1. Description

1.1General Description

The Green source color devices are made with InGaN on Substrate Light Emitting Diode .

Product Package:3.50mmX2.80mmX3.65mm.

InGaN 3.50mmX2.80mmX3.65mm.

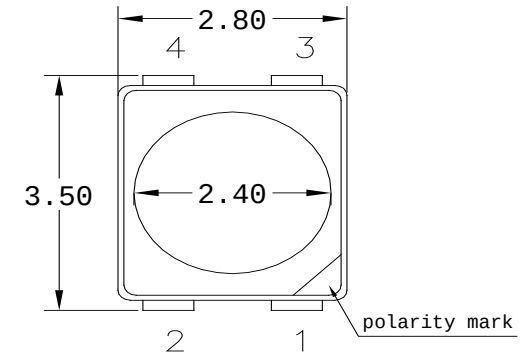
1.2Features

►PLCC4 Package. PLCC4

► extremely narrow angle.

▶Suitable for alleh asse-12(e)37(ib)-14(y)4(nand o)2(l)-14()de ap-20(m)-3(owe)4(s)s]TJ 0 Tc 0 Tw 1..0

1.4Package Dimension



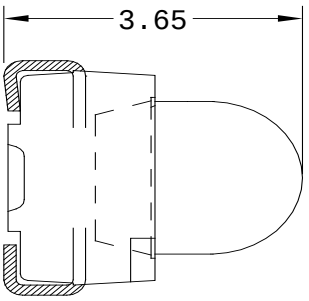
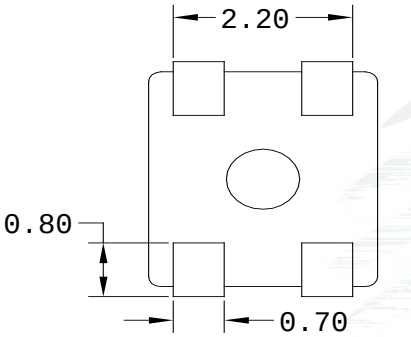
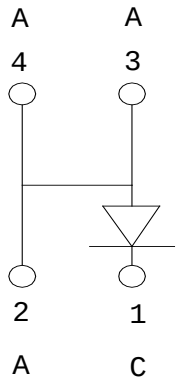
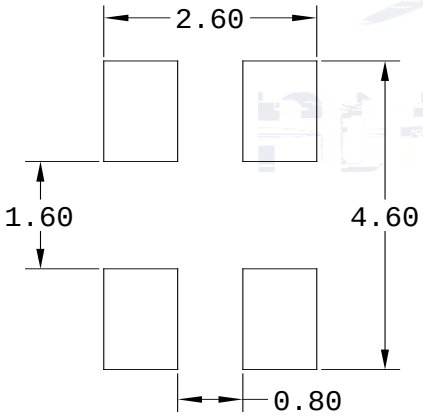


Fig.1-1 Top View







Notes

1. All dimensions units are millimeters.

2. All dimensions tolerances are ±0.2mm unless otherwise noted. 0.2

1.5Product Parameters

Table 1-

Notes

1. 1/10 Duty cycle, 10ms pulse width. 10ms, 1/10.

2. The above forward voltage measurement allowance tolerance is ±0.1V.

3. The above color coordinates measurement allowance tolerance is ±0.005. ± 0.005.

4. The above luminous intensity measurement allowance tolerance ±10%.

5. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.

6. All measurements were made under the standardized environment of Refond.

1.7 Typical Optical Characteristics Curves

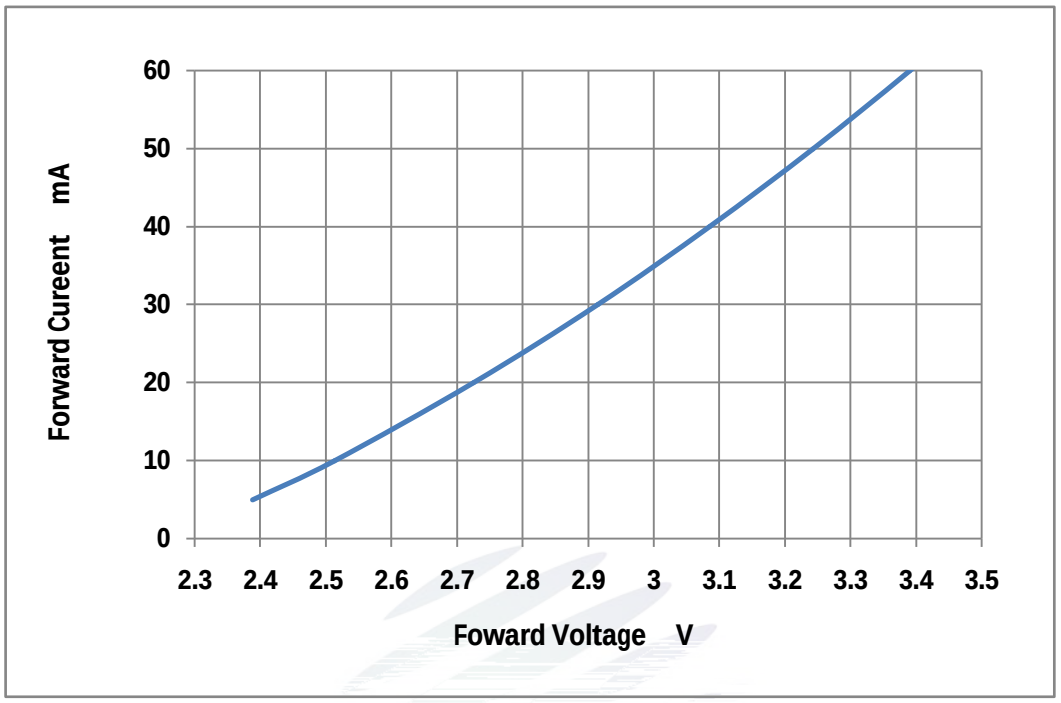


Fig. 1-7 Forward Voltage Vs Forward Current

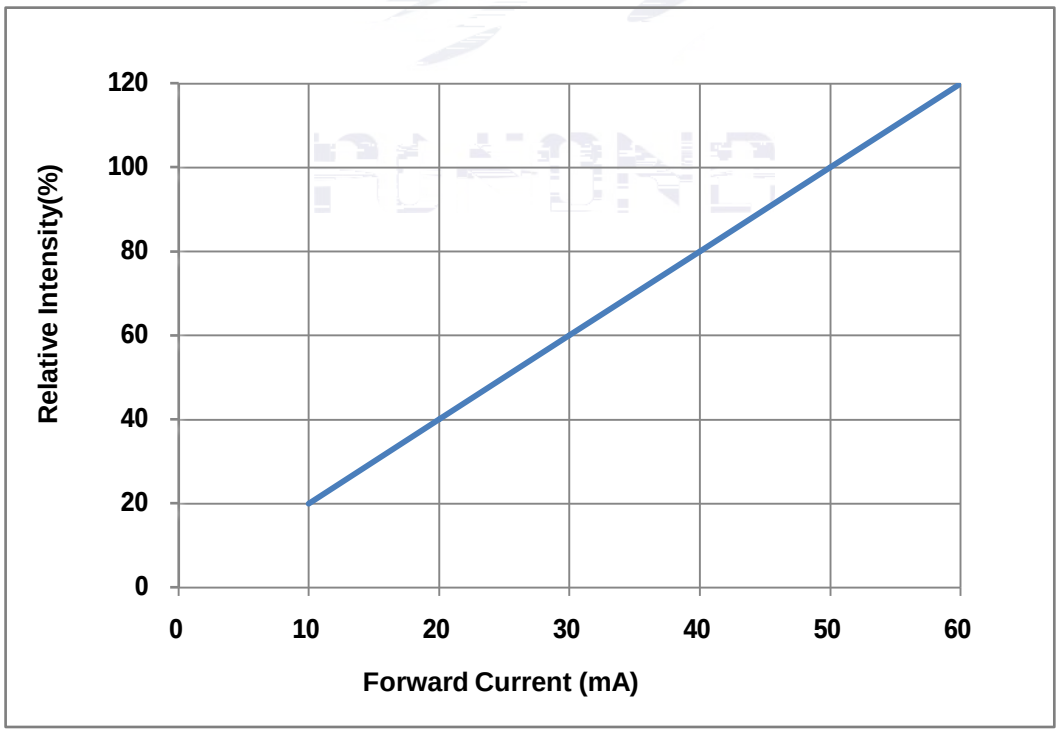


Fig. 1-8 Forward Current Vs Relative Intensity

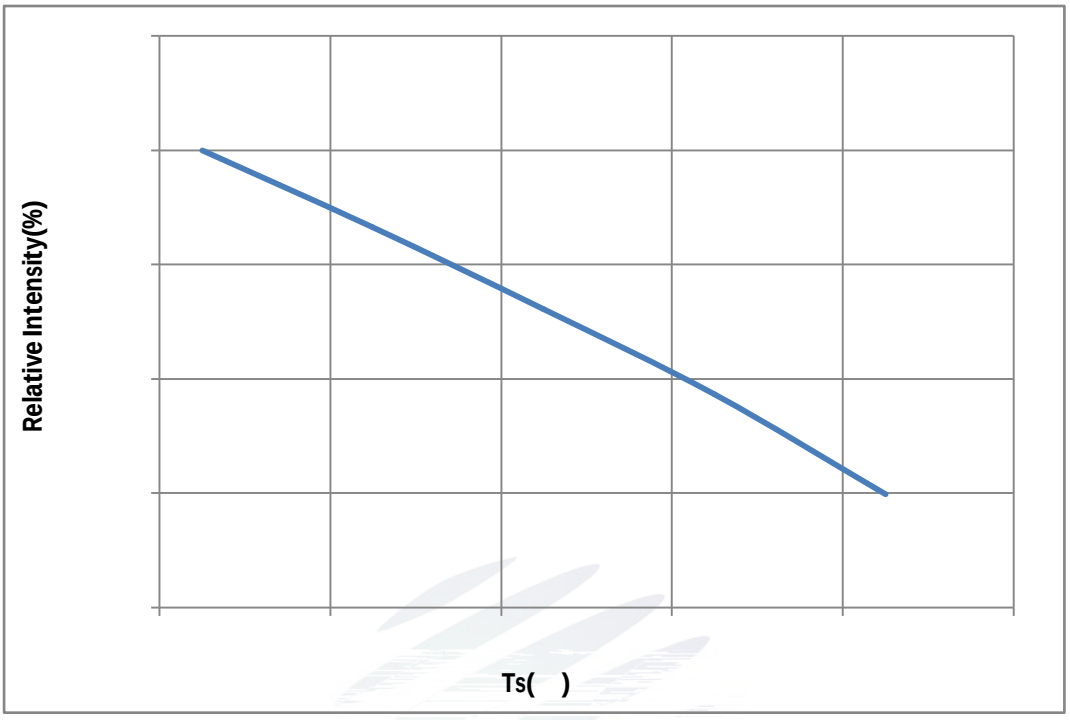


Fig. 1-9 Solder Temperature Vs Relative Intensity

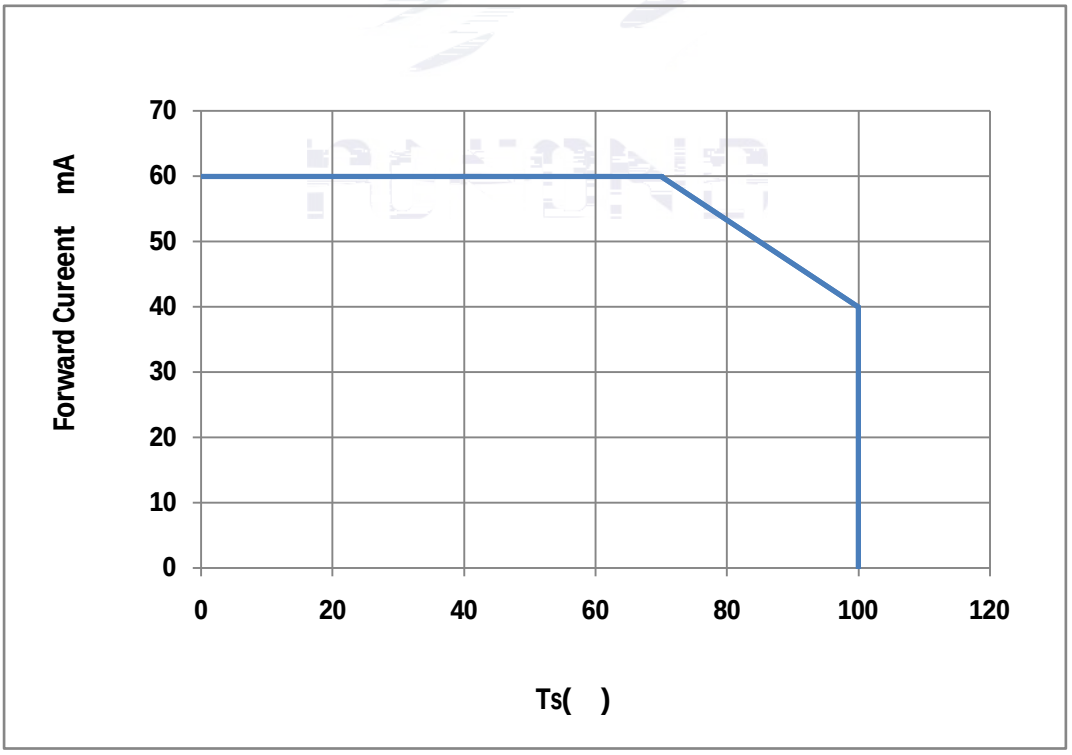


Fig. 1-10 Solder Temperature Vs Forward Current

Fig. 1-11 Forward Voltage Vs Solder Temperature

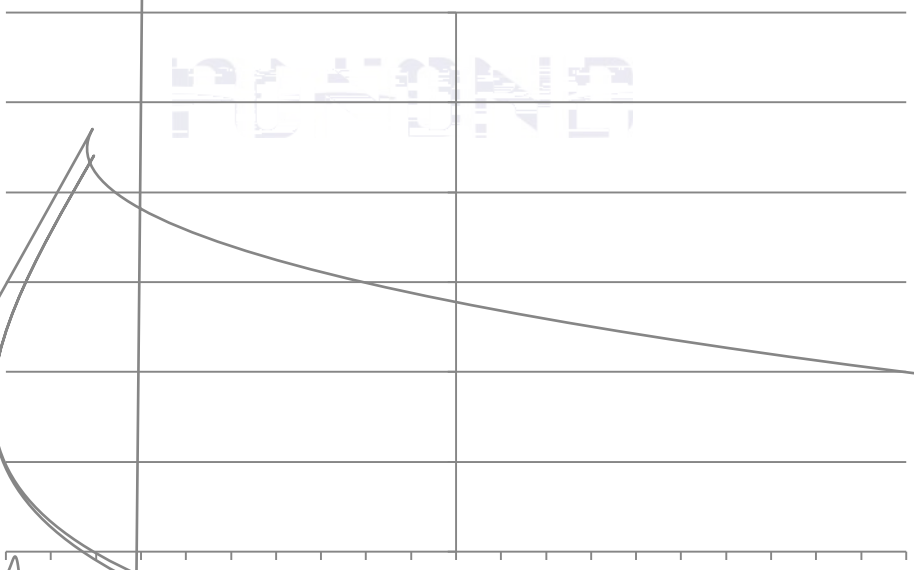


Fig. 1-12 Radiation diagram

2. Packaging

2.1 Packaging Specification

Package:2000pcs/reel.

2.1.1Carrier Tape Dimension

2.1.3Label Form Specification

2- Specification

PART NO.	Part Number
SPEC NO.	Spec Number
LOT NO.	Lot Number
BIN CODE	Bin Code
Φ	Luminous flux
XY	Chromaticity Bin
V_F	Forward Voltage
WLD	Wavelength
QTY	Packing Quantity
DATE	Made Date

Fig. 2-3 Label

2.2Moisture Resistant Packing

Fig.2-4Moisture Resistant Packing

2.3Cardboard Box

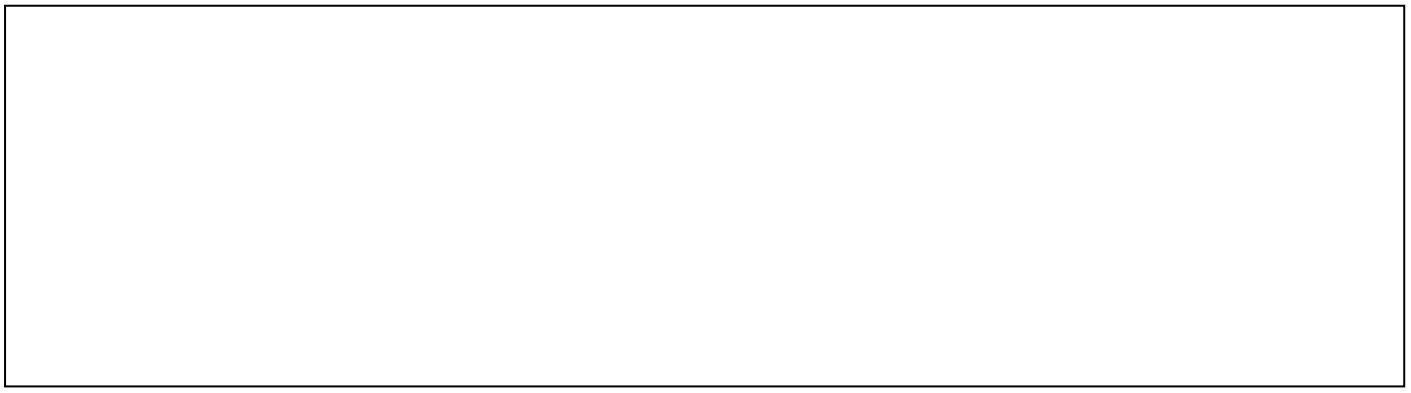


Fig.2-5Cardboard Box

2.4Reliability Test Items And Conditions

Table 2-3 **Reliability Test Items And Conditions**

Test Items	Ref.Standard	Test Condition	Time	Quantity	Ac/Re /
Reflow	JESD22-B106	Temp:260 max T=10 sec	2times	20pcs.	0/1
MSL2 2	JESD22-A113	85 / 60%R_H	168 hrs.	20pcs.	0/1
Thermal Shock	JEITAED-4701 300307	-40 15min ↑↓10s 125 15min	1000 cycle	20pcs.	0/1
Life Test	JESD22-A108	Ta=100 I_F=50mA	1000hrs.	20pcs.	0/1
High Temperature High Humidity Life Test	JESD22-A101	85 / 85%R_H I_F=50mA	1000hrs.	20pcs.	0/1

2.5 Criteria For Judging Damage

Table 2-4**Criteria For Judging Damage**

Test Items	Symbol	Test Condition	Criteria For Judgement	
			Min.	Max.
Forward Voltage	V_F	I_F=50mA	-	U.S.L*)x1.1

3. SMT Reflow Soldering Instructions SMT

3.1SMT Reflow Soldering Instructions SMT

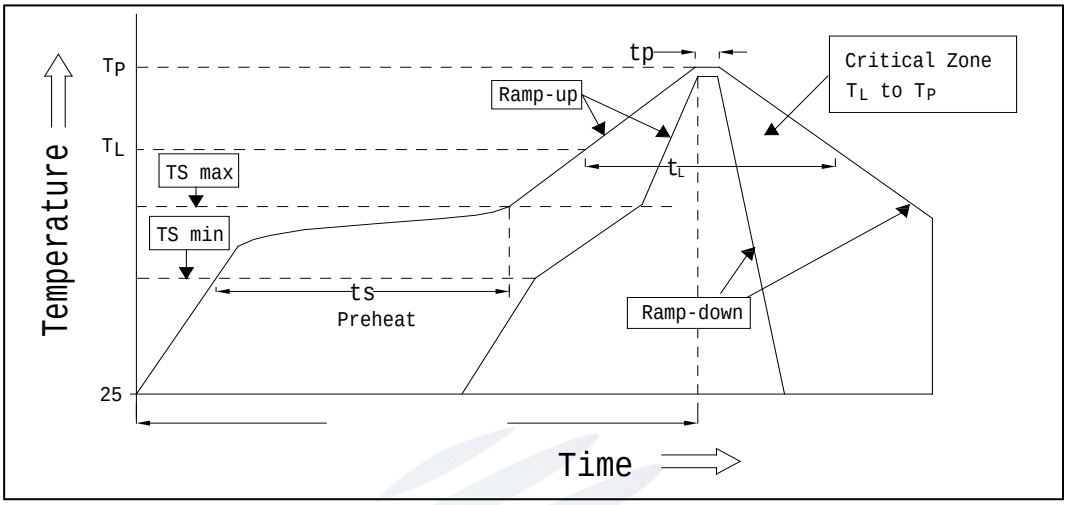


Fig.3-1SMT Reflow Soldering Instructions SMT

Table 3-1Reflow parameters

Average temperature rise speed Tsmax TP	3 °C/ Max 3 °C/ s
Preheating: minimum temperature (Tsmin)	150 °C
Preheating: Max temperature (Tsmax)	200 °C
Preheating: Time Tsmin Tsmax	60 - 120 60s-120s
Time limited to maintain high temperature: the temperature (TL	217 °C
Time limited to maintain high temperature: The Time (tL)	60 Max 60s
Peak /Classification of temperature: / (TP)	260 °C
Time limit classification of peak temperature time tp	10 Max 10s
(TP) 5 °C Hold time within 5 °C with the actual peak temperature (TP)	30 Max 30s
Cooling speed	6 °C/ Max 6 °C/ s
25 °C Needed time from 25 °C to Tp	8 Max 8 minutes

Notes

(1)Reflow soldering should not be done more than twice. If more than 24 hours between the two solderings ,LED will be damaged. 24

(2)When soldering , do not put stress on the LEDs during heating.

3.1.1 Soldering Iron

(1) When do soldering by hand, keep the temperature of iron below less 300 less than 3 seconds.
, 300 3

(2) Soldering by hand should be done only one time.

3.1.2 Repairing

Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable,a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or not be damaged by repairing.

LED LED

3.1.3 Cautions

(1) The encapsulated material of the LEDs is silicone. Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be impacted on the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when use the picking up nozzle, the pressure on the silicone resin should be proper. LED LED

(2) Components should not be mounted on warped (non coplanar) portion of PCB. After soldering, do not warp the circuit board.LED PCB

(3) Do not apply mechanical force or excess vibration during the cooling process to normal temperature after soldering. Do not rapidly cool device after soldering.

4. Handling Precautions

4.1 Handling Precautions

(1) LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material. This is provided for informational purposes only and is not a warranty or endorsement.LED

LED 100PPM.

(2) In order to prevent ex-ternal material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM,the single content of Chlorine elementis required to be less than 900PPM,the total content of Bromine element and Chlorine element in the external materials of the application products is required to be less than 1500PPM. This is provided for informational purposes only and is not a warranty or endorsement. LED LED

900PPM 900PPM

1500PPM.

(3) VOCs (Volatile organic compounds) emitted from materials used in the construction of fixtures can penetrate silicone encapsulants of LEDs and discolor when exposed to heat and photonic energy. The result can be a significant loss of light output from the fixture. Knowledge of the properties of the materials selected to be used in the construction of fixtures can help prevent these issues. Refond advises against the use of any chemicals or materials that have been found or are suspected to have an adverse affect on device performance or reliability. To verify compatibility, Refond recommends that all chemicals and materials be tested in the specific application and environment for which they are intended to be used. Attaching LEDs, do not use adhesives that outgas organic vapor. LED

LED

LED

LED

(4) Handle the component along the side surface by using forceps or appropriate tools; Do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry.

Fig 4-1Handling Precautions

(5) In designing a circuit,thecurrent through each LED can not

Table 4-1Storage

Conditions		Temperature	Humidity	Time
Storage	Before Opening Aluminum Bag	30	75%	Within 1 Year From Date
	After Opening Aluminum Bag	30	60%	Recommended for use within 24 hours 24
Baking		60 5	-	24hours 24

(8) I

Version History/

Date	Revisor	Version	Verifier	Remarks
2022/03/07	ianhui	E0	Z Yiming	

Declare